



GT90SOFT

Soft and Elastic Graphene Enhanced Thermal Interface Material

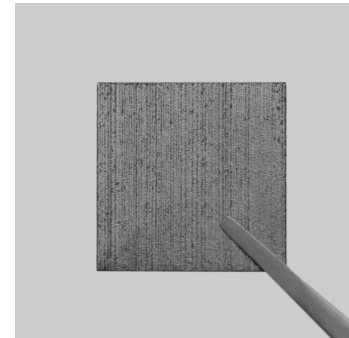
Trademark: GT-TIM®

Features:

- Very High Thermal Conductivity
- Very Low Effective Thermal Resistance
- Very High Compressibility and Recovery

Applications:

Cooling of dataservers, AI chiplet modules, thermal Burn-In, IC thermal functional testing, GPUs, CPUs, and other power devices



Description:

GT90SOFT is a graphene enhanced thermal interface material. It has very low effective thermal resistance (4 Kmm²/W at 275 kPa at 0,2 mm in thickness). Moreover, the GT90SOFT has advantages of high degree of compressibility and recovery and good maintainability. GT90soft opens new opportunities for addressing large heat dissipation issues in electronics and other high power driven systems.

Physical Properties	Value	Units	Test Method
Bulk Thermal Conductivity	90 ± 10 (275KPa,200µm)	W/mK	ASTM5470
Effective Thermal Resistance	4 ± 1 (275 kPa, 200µm)	Kmm ² /W	ASTM5470
Thickness	0.15-0.5	mm	Micrometer
Thickness Tolerance	<10	%	-
Pad Size	Up to 80*80	mm ²	-
Compressibility	>50	%	-
Compressive strength at 50% compression	550±50 (200µm)	kPa	ASTM D575
Recovery	>60	%	-
Tensile strength	>50	kPa	ASTM D412
Surface Roughness (Ra)	5±3	µm	Wyko NT1100 optical profilometer
Surface Roughness (Rz)	30±15	µm	Wyko NT1100 optical profilometer
Application Temperature	-40 to 200	°C	-
Flammability	V-0		UL94
Density	0.60±0.05	g/cm ³	Balance and Micrometer
Color	Grey	-	Visual

GT-TIM® is a protected trademark of Smart High Tech

Smart High Tech

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